



#13/IDS  
4.22.03  
C Moore  
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Agarwal et al.

Art Unit: --

Application No. 10/002,779

Filed: October 29, 2001

For: METHODS FOR FORMING AND  
INTEGRATED CIRCUIT STRUCTURES  
CONTAINING RUTHENIUM AND TUNGSTEN  
CONTAINING LAYERS

Examiner: --

Date: August 21, 2002

CERTIFICATE OF MAILING

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on August 21, 2002 as First Class Mail in an envelope addressed to: COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.

Mr. W ~

\_\_\_\_\_  
Attorney for Applicant

RECEIVED  
APR 18 2003  
TECHNOLOGY CENTER 2800

COMMISSIONER FOR PATENTS  
WASHINGTON, DC 20231

Sir:

Listed on the accompanying Form PTO-1449 are several English-language documents.

Applicants respectfully request that these documents be listed as references cited on the issued patent.

Copies of the references listed on the Form PTO-1449 are not enclosed herewith because they were previously cited by or submitted to the Patent Office in a prior application, serial no. 09/590,795, filed on June 8, 2000, which was relied upon in the present application for an earlier filing date under 35 U.S.C. § 120. This Information Disclosure Statement is being filed before the mailing date of a First Office Action on the merits. Thus, according to 37 C.F.R. § 1.97(b)(3), no fee is required. However, if the Patent Office determines that a fee is required for Applicants

to file this Information Disclosure Statement, please charge any such fees, or credit overpayment,  
to Deposit Account No. 02-4550. A duplicate copy of this Information Disclosure Statement is  
enclosed.

Respectfully submitted,

KLARQUIST SPARKMAN, LLP

By   
Michael D. Jones  
Registration No. 41,879

One World Trade Center, Suite 1600  
121 S.W. Salmon Street  
Portland, Oregon 97204  
Telephone: (503) 226-7391  
Facsimile: (503) 228-9446